



## QuadMo747-X/i.MX6

Computer on Module with Freescale™ i.MX6 Processor



**CPU**  
Single-, Dual- and Quad- Core (ARM Cortex™A9 Cores)



**Memory**  
up to 4GB DDR3L onboard



**Graphics**  
2D/3D dedicated graphics processors



**Temperature**  
Also available in Industrial temperature range, -40°C ÷ +85°C

### FEATURES

<b>Processor</b>	Freescale™ i.MX6 Family, based on ARM Cortex-A9 processors: Single core (i.MX6S) up to 1GHz Dual Core (i.MX6D), Dual Core Lite (i.MX6DL) up to 1.2GHz Quad Core (i.MX6Q) up to 1GHz clock
<b>Max Cores</b>	4
<b>Memory</b>	up to 4GB DDR3L onboard (up to 2GB with i.MX6S)
<b>Graphics</b>	integrated graphics, each processor provides up to 3 separated accelerators for 2D, OpenGL® ES2.0 3D and OpenVG™ (OpenVG™ accelerator only available with i.MX6D and with i.MX6Q) Supports up to 3 independent displays (only up to 2 displays with i.MX6DL and i.MX6S)
<b>Video Interfaces</b>	HDMI interface 1 x Dual Channel or 2 x Single Channel 18/24 bit LVDS interface
<b>Video Resolution</b>	HDMI, up to 1080p LVDS, up to 1920x1200
<b>Mass Storage</b>	1 x SATA interface (only with i.MX6D and i.MX6Q) eMMC soldered onboard MMC/SD/SDIO interface 1 x µSD card slot onboard
<b>Networking</b>	Gigabit Ethernet interface
<b>USB</b>	1x USB OTG 4x USB 2.0 Host
<b>PCI-e</b>	1 x PCI-Express x1 lane
<b>Audio</b>	AC97 Audio Interface
<b>Serial Ports</b>	2 x serial ports CAN Bus interface
<b>Other Interfaces</b>	Video Input Port / Camera Connector LPC BUS or 8 x GPIO SMBus SPI I <sup>2</sup> C bus
<b>Power Consumption</b>	Embedded additional RTC circuitry for lowest power consumption
<b>Operating System</b>	Linux Android Microsoft® Windows® Embedded Compact 7
<b>Operating Temperature*</b>	0°C ÷ +70°C (commercial version) -40°C ÷ +85°C (industrial version)
<b>Dimensions</b>	70 x 70 mm (2,76" x 2,76")

\*Measured at any point of the heatspreader/heatsink during any and all times (including start-up). Actual temperature will widely depend on application, enclosure and/or environment. Upon customer to consider specific cooling solutions for the final system.

### HIGHLIGHTS

- A scalable multi-core ARM® Cortex™-A9 architecture in Qseven® standard modular solution
- Combines and emphasizes high-graphics performance with power-efficient processing capabilities
- OpenGL (FULL) and OpenES 2.0 3D Graphics and up to 3 independent displays (only up to 2 displays with i.MX6DL and i.MX6S)
- Flexible solution enables multi-display platforms to mobile fanless applications



### MAIN FIELDS OF APPLICATION



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